

IN THE CLAIMS:

Please cancel claim 15 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claim 10 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-9. (Cancelled)

10. (Currently Amended) A method of forming CNT emitting sources, said method comprising the steps of:

providing a substrate;

forming a plurality of cathode lines on said substrate;

5 forming a dielectric layer on said substrate and overlaying said cathode lines;

forming a plurality of gate lines on said dielectric layer, said cathodes lines being perpendicular to said gate lines so as to define said pixels; and

10 patterning said dielectric layer over said pixels so as to form openings which expose said cathode lines;

providing an imprint negative mold having a first pattern for imprinting emitting sources;

utilizing said imprint negative mold dipped with CNT paste;

15 using said imprint negative mold imprinting said CNT paste on said cathode lines through said openings; and

curing said CNT paste to form said CNT emitting sources.

wherein said imprint negative mold comprises a trench pattern housing said gate lines so as to prevent the CNT paste adhering to said gate lines while imprinting.

11. (Original) The method according to claim 10 wherein said step of forming cathodes lines is formed by screen print with a silver layer on said substrate.

12. (Original) The method according to claim 10 wherein said step of forming gate lines is formed by screen print with a conductive layer on said dielectric layer.

13. (Original) The method according to claim 10 wherein said gate lines have a spacing between about 30-300 μm in between.

14. (Original) The method according to claim 10 wherein said openings have a depth between 5-50 μm and a width between about 10-100 μm .

15. (Cancelled)

16. (Original) The method according to claim 10 wherein said imprint negative mold comprising an inverse pattern selected from the group consisting of cone, cylinder, star, pyramid and the combination thereof.

17. (Previously Presented) The method according to claim 10 wherein said imprint negative mold is formed comprising the steps of:

providing a first mold material;

5 patterning said first mold material to form an imprint positive mold which comprises patterns for said gate lines and said emitting sources;

injecting a second mold material in liquid state into a mold which encloses said imprint positive mold;

solidifying said second mold material; and

10 drawing said imprint positive mold from said mold so that said imprint negative mold is formed.

Claims 18-19. (Cancelled)